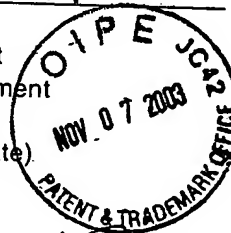


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ENCLOSURES:

- () Application _____
- () Specification _____ pages
- () Claims _____ pages
- () Abstract _____ page(s)
- () Drawing Sheets no. _____ (F) _____ (INF) _____
- () Transmittal Letter
- (x) Check \$ 86.00 No: 15019
- () Declaration/Oath
- () Assignment and Cover Sheet
- () Information Disclosure Statement
- () Response/Amendment
- () Extension of Time (In Duplicate)
- () Small Entity Status
- () Copy of Priority Document
- (x) Preliminary Amendment B



RE: APPLICATION ATTY/SEC: MJM/smw
File no: 0553-0166.01
Applicant: Yamazaki et al

S.N.: 10/629069 Filing Date: July 29, 2003
Wiring material AND A Semiconductor Device
Title: HAVING A Wiring Using The Material AND
The Manufacturing Method Thereof

Due date: _____ Date Sent: 11/4/03

SEL
0553-0166.01
EDM/MJM